

LEADFRAME PACKAGE WITH DUMMY CHIP

Abstract of the Disclosure

5 The lead frame package with dummy chip comprising
a lead frame with a plurality of first leads, molding
compound, a dummy chip and a die. Wherein the molding
compound encapsulates the die and the dummy chip, the
dummy chip is arranged on a lower portion of the
10 molding compound. The die is stacked on an upper
surface of the dummy chip by using an adhesive
material. A plurality of bonding wires are connected
between the die and an end of the plurality of leads
over the dummy chip.

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TOP SECRET